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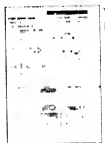
Go to: Derwent

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Title: JP09312459A2: MANUFACTURE OF PRINTED CIRCUIT BOARD WITH THROUGH HOLE**Derwent Title:** PCB manufacturing method - involves developing negatives by projecting visible laser light beam and exposing pattern on substrate through visible laser light exposure type resist layer (Derwent Record)**Country:** JP Japan
Kind: A**Inventor:** TAKEZOE KOJI**Assignee:** KANSAI PAINT CO LTD
News, Profiles, Stocks and More about this company**Published / Filed:** 1997-12-02 / 1996-05-23**Application Number:** JP1996000128654**IPC Code:** Advanced: G03F 7/26; H05K 3/06; H05K 3/42;
Core: more...
IPC-7: G03F 7/26; H05K 3/06; H05K 3/42;**Priority Number:** 1996-05-23 JP1996000128654**Abstract:** PROBLEM TO BE SOLVED: To manufacture a printed circuit board which has no problems of production of dusts and a damaged surface of the printed circuit board at manufacturing, has no defect in throughholes and has fine printed circuit pattern.

SOLUTION: After positive resist ink is filled in a throughhole part of a printed circuit board having the throughhole part, ultraviolet radiation is applied for development to the surface of the printed circuit board to remove the undesired positive resist ink deposited on the surface of the printed circuit board other than its throughhole part thereby removing the undesired positive resist ink and a visible light laser sensing resist layer is formed on the printed circuit board, and a visible light laser beam is exposed onto the visible light laser sensing resist layer in a beam pattern way so as to develop the layer.

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Family: None**Other Abstract Info:** DERABS C98-074196 DERC98-074196

Abstract

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